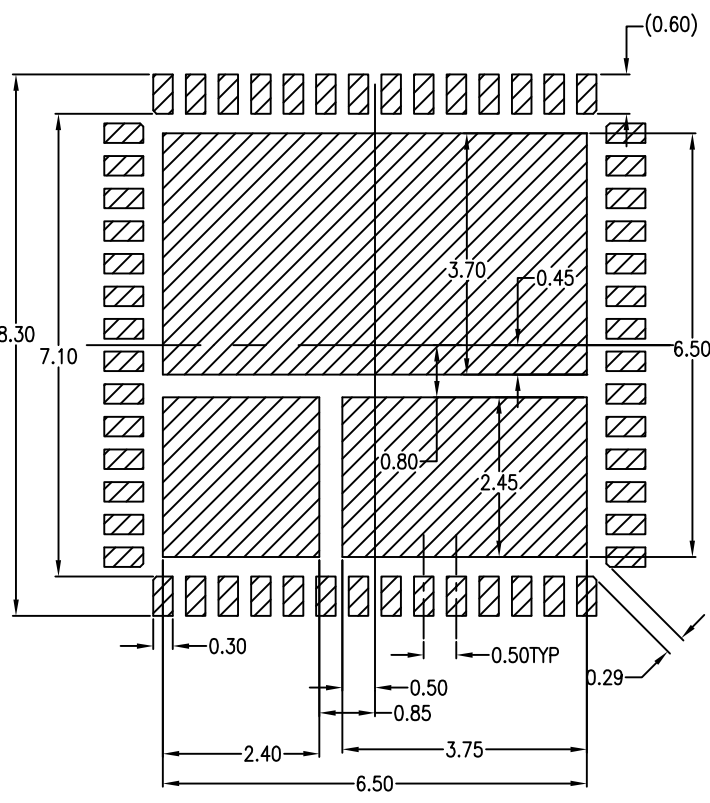
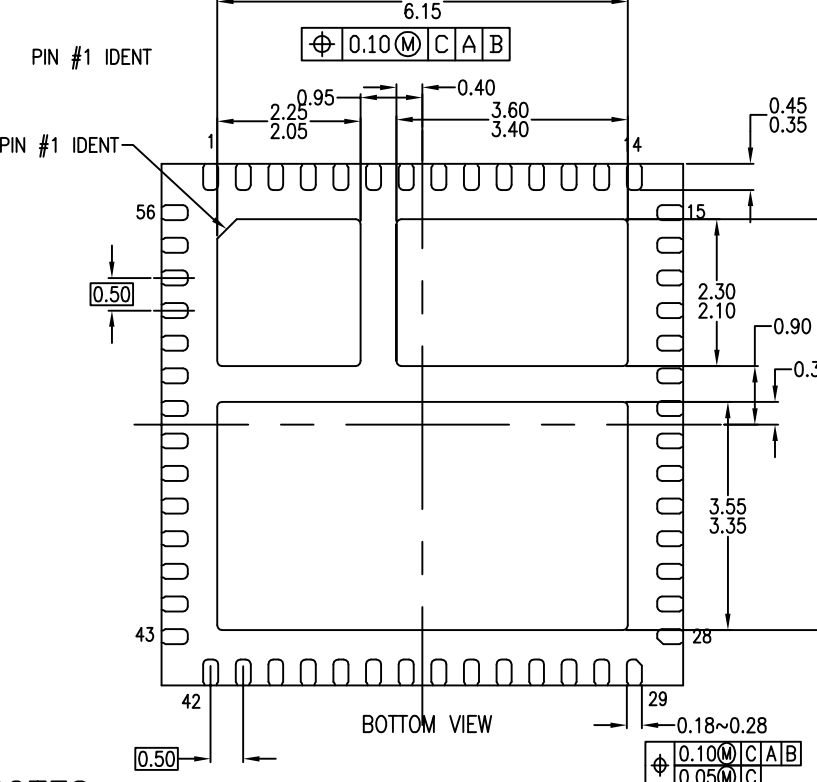
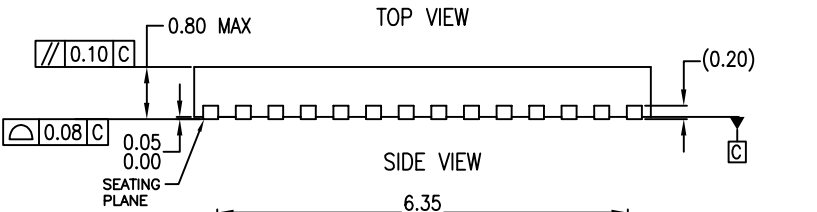
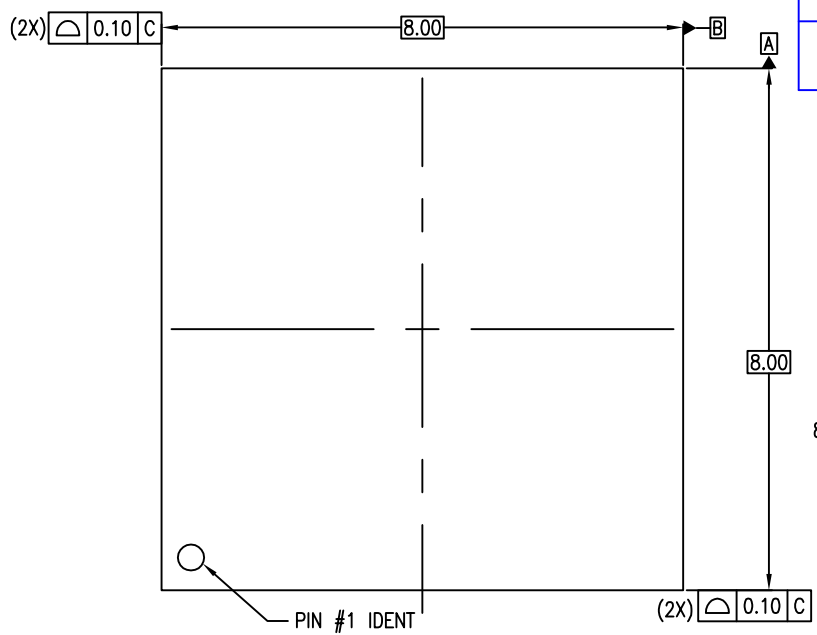


REVISIONS				
LTR	DESCRIPTION	EDCN	DATE	BY/APP'D
1	Released to Document Control	106769	22/03/07	LY LIM



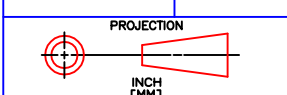
NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-220, VARIATION wlld-5 EXCEPT FOR THERMAL PAD SIZES
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE NOT INCLUSIVE OF BURRS, MOLD FLASH, NOR TIE BAR PROTRUSIONS.
- D. DRAWING FILE NAME ; MLP056REV1

APPROVALS	DATE
DRAWN Ly Lim	3-14-2006
DETG. CHK. David Chong	3-14-2006
ENGR. CHK. David Chong	3-14-2006

FAIRCHILD SEMICONDUCTOR™
 Bayan Lepas FIZ
 11900, Penang, Malaysia

56LD, MLP, QUAD, JEDEC
 MO-220 VAR WLLD-5,6, 8X8 MM



SCALE	SIZE	DRAWING NUMBER	REV
N/A	N/A	MKT-MLP056B	1

DO NOT SCALE DRAWING SHEET 1 of 1